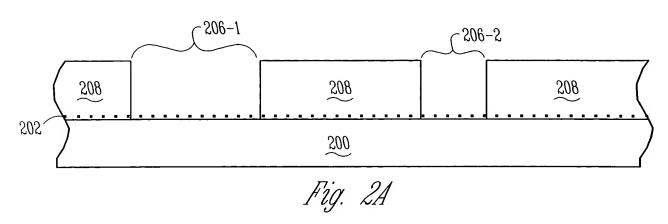
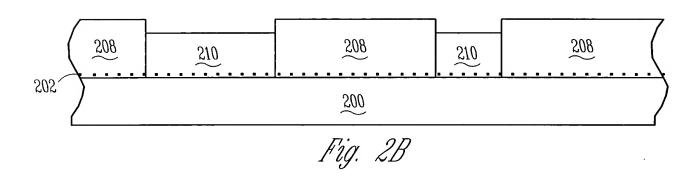
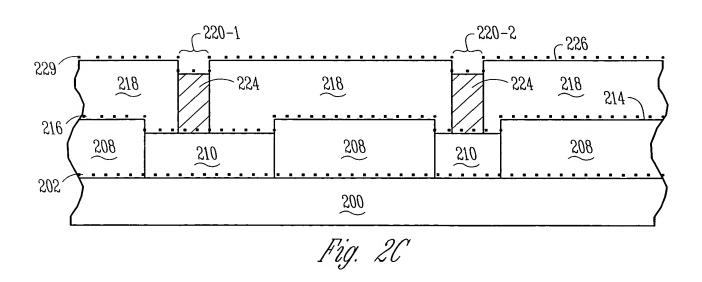


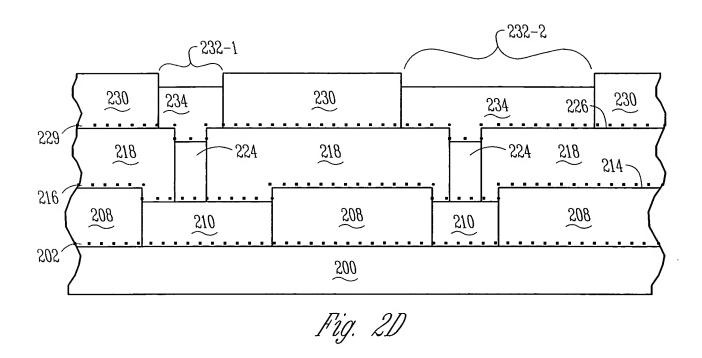
2/5







3/5



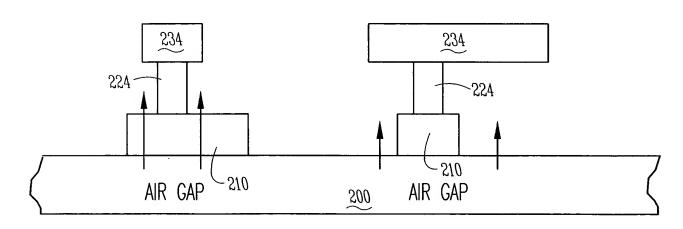


Fig. 2E

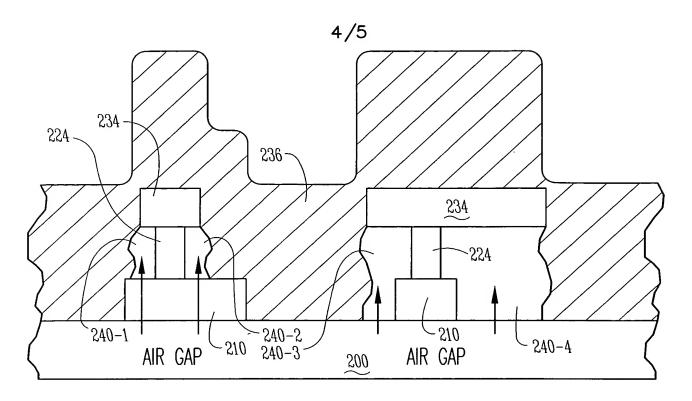
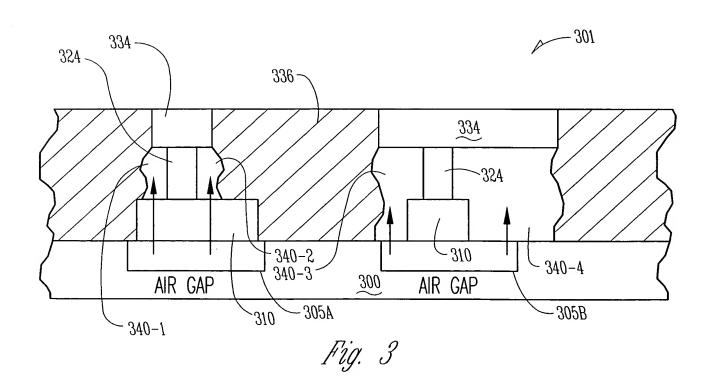


Fig. 2F



TITLE: MULTILEVEL, COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS INVENTORS NAME: Kie Y. Ahn et al. DOCKET NO.: 303.686US3

5/5

